

## PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

## CONVEYING PARTY DATA

Name	Execution Date
Isamu KONISHIIKE	07/15/2008
Chisato OKINA	07/16/2008
Keisuke TANABE	07/16/2008
Atsuhiko ABE	07/16/2008
Hidetoshi NISHIYAMA	07/17/2008
Kenichi KAWASE	07/23/2008
Shunsuke KURASAWA	07/23/2008
Koichi MATSUMOTO	07/23/2008

## RECEIVING PARTY DATA

Name:	SONY CORPORATION
Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12197731

## CORRESPONDENCE DATA

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PATENT  
REEL: 021449 FRAME: 0603

ATTORNEY DOCKET NUMBER:	330993US8
NAME OF SUBMITTER:	Ronald Turner
Total Attachments: 3 source=330993USASSIGN#page1.tif source=330993USASSIGN#page2.tif source=330993USASSIGN#page3.tif	

Docket Number: \_\_\_\_\_

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in EVAPORATION APPARATUS, METHOD OF MANUFACTURING ANODE USING SAME, AND METHOD OF MANUFACTURING BATTERY USING SAME for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_.

This assignment executed on the dates indicated below.

Isamu KONISHIIKE

Name of first or sole inventor

July 15, 2008

Execution date of U.S. Patent Application

Fukushima, Japan

Residence of first or sole inventor

Isamu Konishiike

Signature of first or sole inventor

July 15, 2008

Date of this assignment

Chisato OKINA	July 16. 2008
Name of second inventor	Execution date of U.S. Patent Application
Miyagi, Japan	
Residence of second inventor	
Chisato Okina	July 16. 2008
Signature of second inventor	Date of this assignment

Keisuke TANABE	July 16. 2008
Name of third inventor	Execution date of U.S. Patent Application
Miyagi, Japan	
Residence of third inventor	
Keisuke Tanabe	July 16. 2008
Signature of third inventor	Date of this assignment

Atsuhiko ABE	July 16. 2008
Name of fourth inventor	Execution date of U.S. Patent Application
Miyagi, Japan	
Residence of fourth inventor	
Atsuhiko Abe	July 16. 2008
Signature of fourth inventor	Date of this assignment

Hidetoshi NISHIYAMA	July 17. 2008
Name of fifth inventor	Execution date of U.S. Patent Application
Miyagi, Japan	
Residence of fifth inventor	
Hidetoshi Nishiyama	July 17. 2008
Signature of fifth inventor	Date of this assignment

Kenichi KAWASE

July 23, 2008  
Execution date of U.S. Patent Application

Name of sixth inventor

Fukushima, Japan

Residence of sixth inventor

Kenichi Kawase  
Signature of sixth inventorJuly 23, 2008  
Date of this assignment

Shunsuke KURASAWA

July 23, 2008  
Execution date of U.S. Patent Application

Name of seventh inventor

Fukushima, Japan

Residence of seventh inventor

Shunsuke Kurasawa  
Signature of seventh inventorJuly 23, 2008  
Date of this assignment

Koichi MATSUMOTO

July 23, 2008  
Execution date of U.S. Patent Application

Name of eighth inventor

Fukushima, Japan

Residence of eighth inventor

Koichi Matsumoto  
Signature of eighth inventorJuly 23, 2008  
Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment